MRA4003T3 Series

Surface Mount Standard Recovery Power Rectifier

SMA Power Surface Mount Package

Features construction with glass passivation. Ideally suited for surface mounted automotive applications.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Stable, High Temperature, Glass Passivated Junction
- Pb–Free Packages are Available

Mechanical Characteristics

- Case: Molded Epoxy Epoxy meets UL 94 V-0 @ 0.125 in
- Weight: 70 mg (Approximately)
- Finish: All External Surfaces are Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 seconds in Solder Bath
- Polarity: Band in Plastic Body Indicates Cathode Lead
- Marking: MRA4003T3 = R13
 - MRA4004T3 = R14 MRA4005T1 = R15 MRA4005T3 = R15 MRA4006T3 = R16 MRA4007T3 = R17

MAXIMUM RATINGS

Please See the Table on the Following Page



ON Semiconductor®

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STANDARD RECOVERY RECTIFIERS 1.0 AMPERES 300–1000 VOLTS



CASE 403D SMA PLASTIC

MARKING DIAGRAM



 R1x
 = Specific Device Code

 A
 = Assembly Location

 Y
 = Year

 WW
 = Work Week

 •
 = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the ordering information section on page 4 of this data sheet.

MRA4003T3 Series

MAXIMUM RATINGS

		Value					
Rating	Symbol	MRA4003T3	MRA4004T3	MRA4005T1, MRA4005T3	MRA4006T3	MRA4007T3	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	300	400	600	800	1000	Volts
Avg. Rectified Forward Current (At Rated V _R , T _L = 150°C)	Ι _Ο	1				Amp	
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _L = 150°C)	I _{FRM}	2					Amps
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I _{FSM}	30					Amps
Storage/Operating Case Temperature	T _{stg} , T _C	-55 to 150				°C	
Operating Junction Temperature	TJ	-55 to 175				°C	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	R _{θJL}	16.2	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJA}	88.3	

ELECTRICAL CHARACTERISTICS

		Value		
Characteristic	Symbol	T _J = 25°C	T _J = 100°C	Unit
Maximum Instantaneous Forward Voltage (Note 3) (I _F = 1 A) (I _F = 2 A)	V _F	1.1 1.18	1.04 1.12	Volts
Maximum Instantaneous Reverse Current (at rated DC voltage)	I _R	10	50	μΑ

1. Minimum Pad Size

2. 1 inch Pad Size

3. Pulse Test: Pulse Width \leq 250 µs, Duty Cycle \leq 2%.



Figure 1. Typical Forward Voltage

Figure 2. Typical Reverse Current



Figure 6. Thermal Response

MRA4003T3 Series

ORDERING INFORMATION

Device	Package	Shipping†
MRA4003T3	SMA	5000/Tape & Reel
MRA4003T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4004T3	SMA	5000/Tape & Reel
MRA4004T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4005T1	SMA	1500/Tape & Reel
MRA4005T1G	SMA (Pb-Free)	1500/Tape & Reel
MRA4005T3	SMA	5000/Tape & Reel
MRA4005T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4006T3	SMA	5000/Tape & Reel
MRA4006T3G	SMA (Pb-Free)	5000/Tape & Reel
MRA4007T3	SMA	5000/Tape & Reel
MRA4007T3G	SMA (Pb-Free)	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SMA CASE 403D-02 ISSUE C



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 403D-01 OBSOLETE, NEW STANDARD IS 403D-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.91	2.16	2.41	0.075	0.085	0.095	
A1	0.05	0.10	0.15	0.002	0.004	0.006	
b	1.27	1.45	1.63	0.050	0.057	0.064	
С	0.15	0.28	0.41	0.006	0.011	0.016	
D	2.29	2.60	2.92	0.090	0.103	0.115	
E	4.06	4.32	4.57	0.160	0.170	0.180	
HE	4.83	5.21	5.59	0.190	0.205	0.220	
L	0.76	1.14	1.52	0.030	0.045	0.060	



SOLDERING FOOTPRINT*

A



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.